

## Specifications

Insulation Resistance:	500M $\Omega$ at 150V DC
Withstanding Voltage:	100V <sub>eff</sub> to 700V <sub>eff</sub> for 1 minute
Contact Resistance:	30m $\Omega$ max. at 10mA and 20mV
Operating Temp. Range:	-25°C to +85°C
Reflow-soldering Temp.:	220°C for 60 seconds
Mating Cycles:	20 insertions maximum
Solvent Durability:	Freon
Allowable Torque (max.):	- for 1-time screw connection = max 0.147 Nm - for repetitive screw connection = min 0.078 Nm max 0.098 Nm

## Materials and Finish

Housing: Polyphenylenesulfide (PPS) glass filled UL94V-0  
 Contact: Beryllium Copper (BeCu)  
 Plating: SnPb 2.0 ~ 4.0 $\mu$ m over 2.5 ~ 4.5 $\mu$ m Ni = S5  
 Au 0.3 $\mu$ m min. over 2.5 ~ 4.5 $\mu$ m Ni = B5

## Part Number (Details)

IC149 - 100 - \*25 - \*5

Series No.

No. of Contact Pins

Positioning Pins:

0 = Without Pins

1 = With Pins

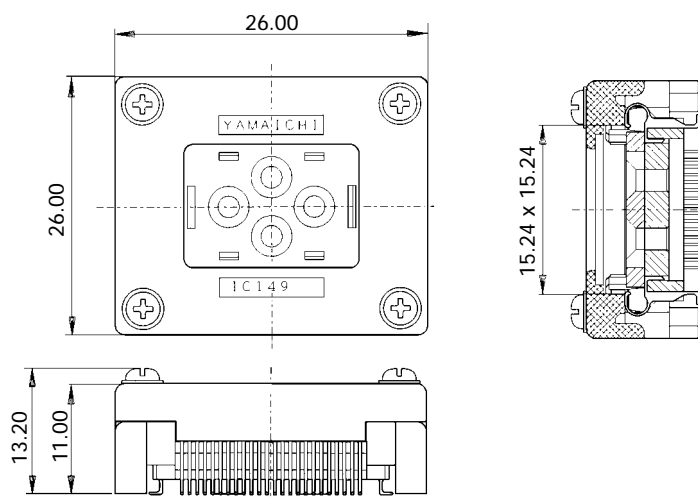
Contact Plating:

S = SnPb (for IC-socket Use)

B = Gold (for Adapter Use)

## Compatible Emulation-Adapter ICP-100-5

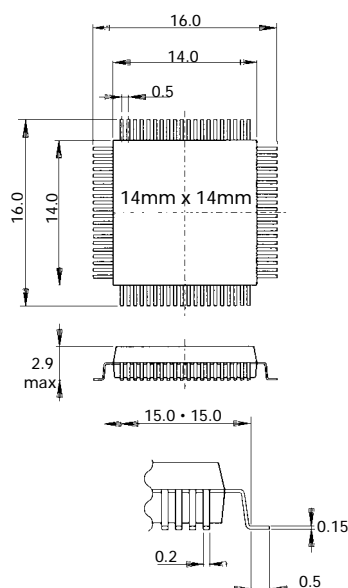
## Outline Socket Dimensions (Reference Only)



### Remarks

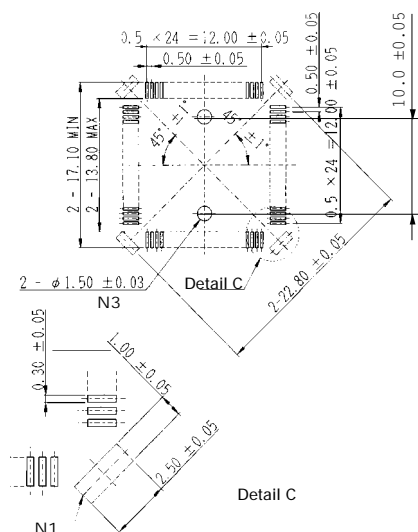
1. Ensure a clean contact area. Fluxes, dust and other impurities may cause corrosion and contact problems.
2. This Socket is not for automatic production. It is particularly suitable for the development of software stored in ROM and for testing LSI-IC's.
3. Careful attention must be taken when fixing the Socket, since it is entirely made from thermoplastic material. If the max. torque is exceeded, the Socket will be damaged beyond repair.
4. If using the Socket with an Adapter, please use the gold-plated Socket version.

## IC - Dimensions



## Socket PCB-Layout

Top View from Socket



### Notes

- N1: Metal soldering Tab Clip. Socket may be stabilized by soldering (Reflow) in these 4 areas.  
 N3: These holes are only necessary for use with positioning pins.

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Allowable Torque (max.):	- for 1-time screw connection = max 0.147 Nm - for repetitive screw connection = min 0.078 Nm max 0.098 Nm

## Materials and Finish

Housing: Polyphenylenesulfide (PPS) glass filled UL94V-0  
 Contact: Beryllium Copper (BeCu)  
 Plating: SnPb 2.0 ~ 4.0μm over 2.5 ~ 4.5μm Ni = S5  
 Au 0.3μm min. over 2.5 ~ 4.5μm Ni = B5

## Part Number (for IC-use)

IC149 - 100 - \*28 - \*5

Series No.

No. of Contact Pins

Positioning Pins:

0 = Without Pins

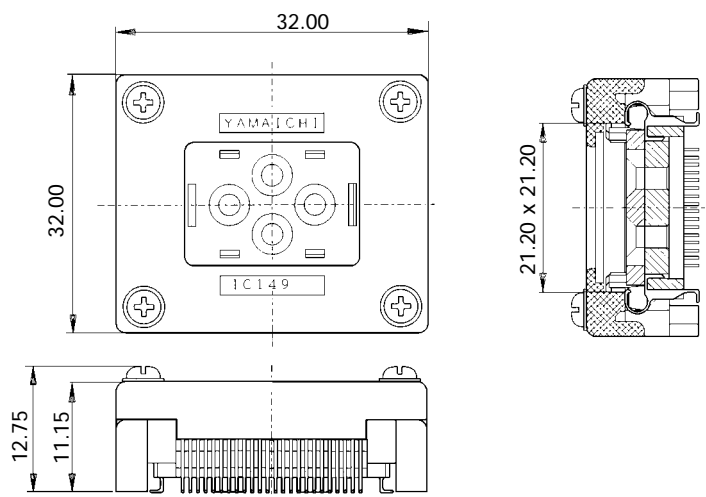
1 = With Pins

Contact Plating:

S5 = SnPb B5 = Au Plating

## Compatible Emulation-Adapter ICP-100-6

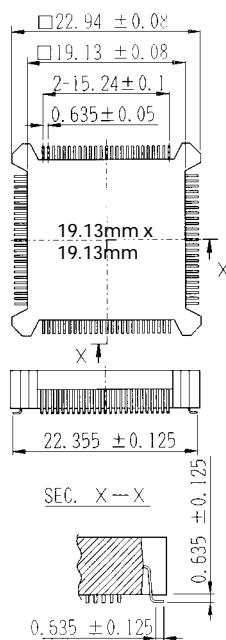
## Outline Socket Dimensions (Reference Only)



### Remarks

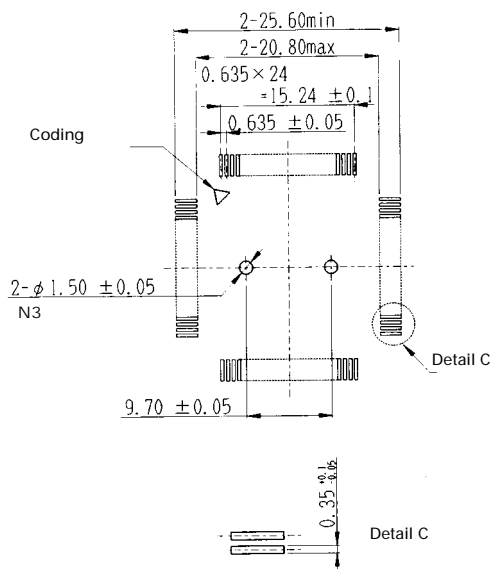
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4. If using the Socket with an Adapter, please use the gold-plated Socket version.

## IC - Dimensions



## Socket PCB-Layout

Top View from Socket



### Notes

N3: These holes are only necessary for use with positioning pins.

## Specifications

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Contact Resistance:	30mΩ max. at 10mA and 20mV
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Reflow-soldering Temp.:	220°C for 60 seconds
Mating Cycles:	20 insertions maximum
Solvent Durability:	Freon
Allowable Torque (max.):	- for 1-time screw connection = max 0.147 Nm - for repetitive screw connection = min 0.078 Nm max 0.098 Nm

## Materials and Finish

Housing: Polyphenylenesulfide (PPS) glass filled UL94V-0  
 Contact: Beryllium Copper (BeCu)  
 Plating: SnPb 2.0 ~ 4.0μm over 2.5 ~ 4.5μm Ni = S5  
 Au 0.3μm min. over 2.5 ~ 4.5μm Ni = B5

## Part Number (Details)

IC149 - 100 - \*14 - \*5

Series No.

No. of Contact Pins

Positioning Pins:

0 = Without Pins

1 = With Pins

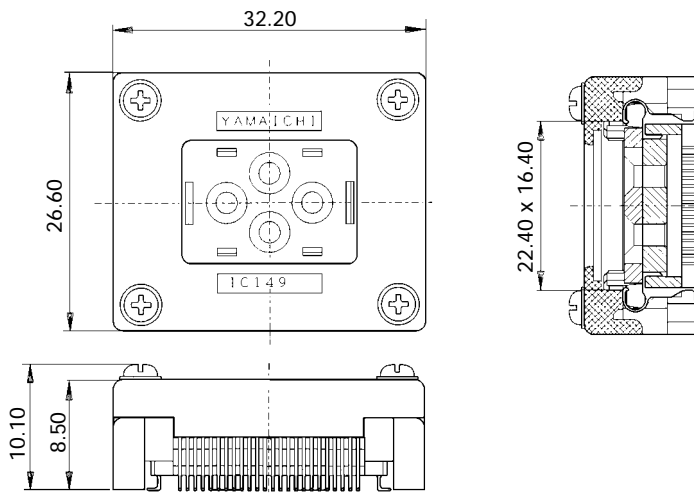
Contact Plating:

S = SnPb (for IC-socket Use)

B = Gold (for Adapter Use)

## Compatible Emulation-Adapter ICP-100-4-4 (with 4 x M2.0 -12.0mm)

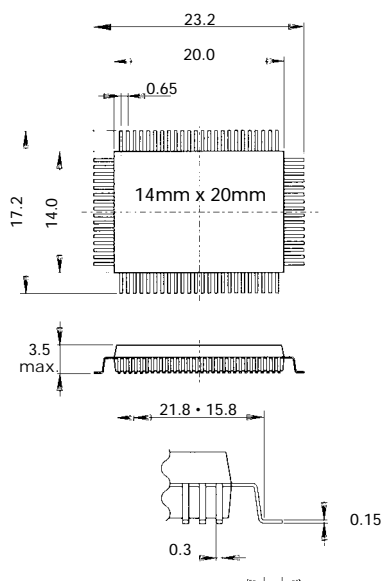
## Outline Socket Dimensions (Reference Only)



### Remarks

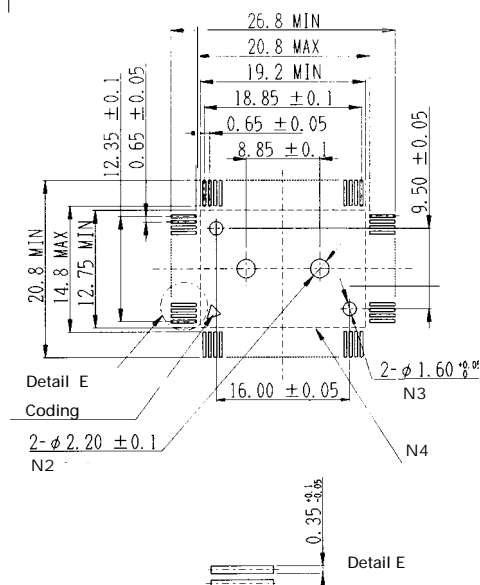
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## IC - Dimensions



## Socket PCB-Layout

Top View from Socket



### Notes

- N2: These holes are only necessary when fixing the Socket with screws.  
 N3: These holes are only necessary for use with positioning pins.  
 N4: The Socket may be glued to the PC Board within this area.

## Specifications

Insulation Resistance:	500MΩ at 150V DC
Withstanding Voltage:	100V <sub>eff</sub> to 700V <sub>eff</sub> for 1 minute
Contact Resistance:	30mΩ max. at 10mA and 20mV
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Solvent Durability:	Freon

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Plating:	SnPb 2.0 ~ 4.0μm over 2.5 ~ 4.5μm Ni = S5 Au 0.3μm min. over 2.5 ~ 4.5μm Ni = B5

Extra Feature: Clipped Cover

## Part Number (for IC-use)

IC149 - 100 - \*05 - S5

Series No.

No. of Contact Pins

Positioning Pins:

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1 = With Pins

Contact Plating:

S = SnPb

## Part Numbers (for Adapter-use)

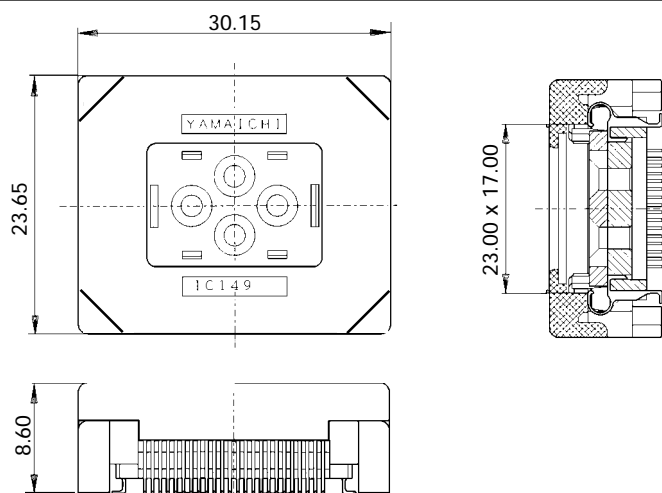
IC149-100-KS11113-0 (w/o pos. pins)

IC149-100-KS11113-1 (with pos. pins)

## Compatible Emulation-Adapter

ICP-100-4-1\* (for IC149-100\*KS only)

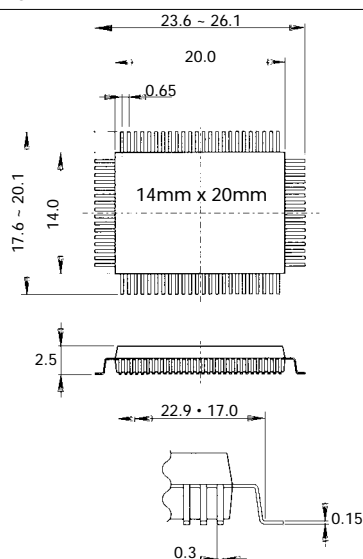
## Outline Socket Dimensions (Reference Only)



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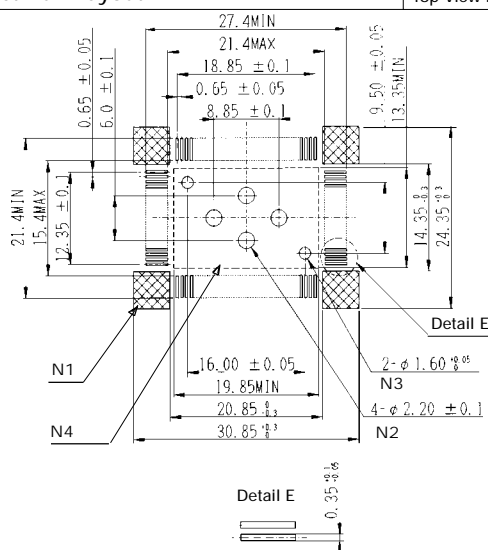
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